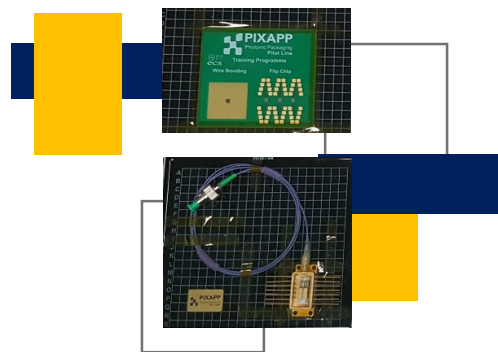


Advanced Packaging and Assembly Training Programme

PIXAPP, Europe's Photonic Integrated Circuit (PIC) Packaging Pilot Line, is pleased to announce roll-out of its advanced PIC design, fabrication and packaging training programme. This unique industry training programme provides attendees with access to state-of-the-art facilities and equipment, and a comprehensive set of dedicated lectures and technical mentoring.



PIXAPP Educational Demonstrators

The programme is delivered by international experts coming from PIXAPP European Consortium (industrial and research), ensuring attendees gain a deep understanding of PIC technologies and critical PIC packaging manufacturing processes.



Register online
your interest to
participate

Training Programme Topics

- PIC Device & Package Design (lectures and design software training).
- PIC Fabrication (lectures and lab-based training).
- PIC Assembly and Packaging (lectures and lab-based training).
- PIC Testing, Product Reliability and Failure Analysis (lecture and lab-based demonstration).
- PIXAPP Demonstrators and Building Blocks.

For more information, visit our website:

<https://pixapp.eu/>

Or contact us via email: info@pixapp.eu



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